



PS-234 I

Product Description:

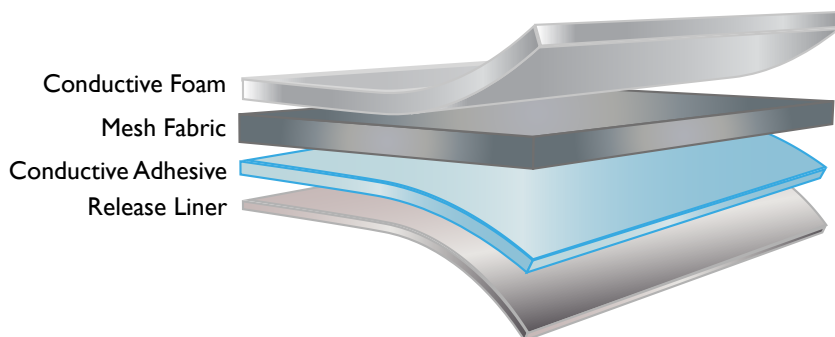
P-SHIELD® PS-234 I is a nickel and copper plated ultra soft version of our conductive polyurethane foam multi-laminate containing a copper nickel mesh core to provide excellent conductivity in all axes as well as structure and restitution. This softness reduces forces on the adjacent components during compression while providing a good grounding path.

Construction / Properties:

Property	Value	Test Method
Total Thickness	4.5mm, 5.0mm, 6.0mm, 7.0mm	QSP-726
Total Thickness Tolerance	+/- 5%	--
Color	Gray	Visual
Adhesive Peel Strength (to SUS)	1000 g/25mm	QSP-722
Recommended Application Specification	2 kg/square inch pressure for 2 seconds	--
Surface Resistivity	<2.0 Ω/sq	QSP-74 I
Z-Axis Resistivity	<1.5 Ω/in ²	QSP-74 I
Shielding Effectiveness (30 MHz - 1.5GHz)	> 65 dB	--
Continuous Use Conditions	-20 - 120 C	QSP-754

Features:

- Excellent Tack
- Excellent Conductive Properties
- Excellent Adhesion to Low Energy Substrates
- Excellent Shielding Effectiveness to Low Energy Substrates
- Good Resistance to Heat and Humidity
- RoHS and HF Compliant



Specific tests should be performed by the end user to determine the product stability for the particular application.

For Additional Information:

E-mail: sales@polymerscience.com
Toll Free: +1 888.533.7004
Web: www.polymerscience.com
Revision: 052322